

Abstract

A system for fabricating semiconductor components
5 includes mating mold cavity plates having mold cavities
configured to mold body segments of the semiconductor
components on either side of a leadframe. The mold cavity
plates also include runners configured to direct molding
compound between the mold cavities and into the corners of
10 the mold cavities. The runners prevent trapped air from
accumulating in the corners of the mold cavities, and
eliminate the need for air vents in the corners. The mold
cavity plates also include dummy mold cavities configured to
15 form dummy segments on the leadframe, and air vents in flow
communication with the dummy segments. The dummy mold
cavities are configured to collect trapped air, and to direct
the trapped air through the air vents to atmosphere. Each
20 dummy mold cavity has only a single associated air vent, such
that cleaning is facilitated, and flash particles from the
air vents are reduced. A method for fabricating
semiconductor components includes a molding step performed
using the system. A semiconductor component fabricated using
25 the system includes the leadframe, a die, upper and lower
body segments encapsulating the die, and dummy segments on
the leadframe.